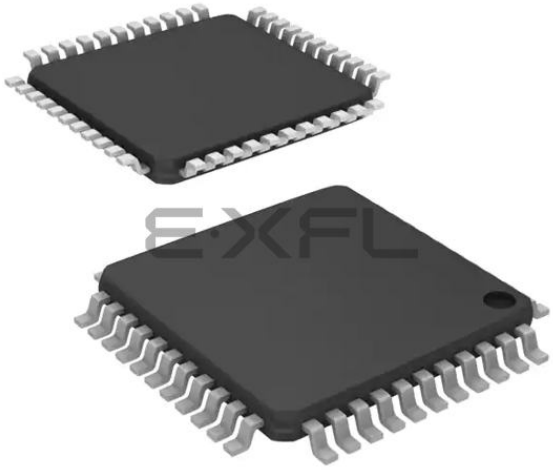

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	34
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2.15V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f46j53-i-pt

TABLE 1-4: PIC18F4XJ53 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number		Pin Type	Buffer Type	Description
	44-QFN	44-TQFP			
					PORTE is a bidirectional I/O port.
RE0/AN5/PMRD	25	25			
RE0			I/O	ST/DIG	Digital I/O.
AN5			I	Analog	Analog Input 5.
PMRD			I/O	ST/TTL/DIG	Parallel Master Port input/output.
RE1/AN6/PMWR	26	26			
RE1			I/O	ST/DIG	Digital I/O.
AN6			I	Analog	Analog Input 6.
PMWR			I/O	ST/TTL/DIG	Parallel Master Port write strobe.
RE2/AN7/PMCS	27	27			
RE2			I/O	ST/DIG	Digital I/O.
AN7			I	Analog	Analog Input 7.
PMCS			O	DIG	Parallel Master Port byte enable.
VSS1	6	6	P	—	Ground reference for logic and I/O pins.
VSS2	31	29	—	—	
AVSS1	30	—	P	—	Ground reference for analog modules.
VDD1	8	7	P	—	Positive supply for peripheral digital logic and I/O pins.
VDD2	29	28	P	—	
VDDCORE/VCAP	23	23			Core logic power or external filter capacitor connection.
VDDCORE			P	—	Positive supply for microcontroller core logic (regulator disabled).
VCAP			P	—	External filter capacitor connection (regulator enabled).
AVDD1	7	—	P	—	Positive supply for analog modules.
AVDD2	28	—	—	—	Positive supply for analog modules.
VUSB	37	37	P	—	USB voltage input pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to VDD); DIG = Digital output; I^2C = Open-Drain, I^2C specific

Note 1: RA7 and RA6 will be disabled if OSC1 and OSC2 are used for the clock function.

2: Available only on 44-pin devices (PIC18F46J53, PIC18F47J53, PIC18LF46J53 and PIC18LF47J53).

3: 5.5V tolerant.

REGISTER 9-15: IPR2: PERIPHERAL INTERRUPT PRIORITY REGISTER 2 (ACCESS FA2h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
OSCFIP	CM2IP	CM1IP	USBIP	BCL1IP	HLVDIP	TMR3IP	CCP2IP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **OSCFIP:** Oscillator Fail Interrupt Priority bit
1 = High priority
0 = Low priority

bit 6 **CM2IP:** Comparator 2 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 5 **C12IP:** Comparator 1 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 4 **USBIP:** USB Interrupt Priority bit
1 = High priority
0 = Low priority

bit 3 **BCL1IP:** Bus Collision Interrupt Priority bit (MSSP1 module)
1 = High priority
0 = Low priority

bit 2 **HLVDIP:** High/Low-Voltage Detect Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **TMR3IP:** TMR3 Overflow Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **CCP2IP:** ECCP2 Interrupt Priority bit
1 = High priority
0 = Low priority

9.5 RCON Register

The RCON register contains bits used to determine the cause of the last Reset or wake-up from Idle or Sleep mode. RCON also contains the bit that enables interrupt priorities (IPEN).

REGISTER 9-19: RCON: RESET CONTROL REGISTER (ACCESS FD0h)

R/W-0	U-0	R/W-1	R/W-1	R-1	R-1	R/W-0	R/W-0
IPEN	—	$\overline{CM}$	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IPEN:** Interrupt Priority Enable bit
1 = Enable priority levels on interrupts
0 = Disable priority levels on interrupts (PIC16CXXX Compatibility mode)

bit 6 **Unimplemented:** Read as '0'

bit 5 **$\overline{CM}$:** Configuration Mismatch Flag bit
For details on bit operation, see Register 5-1.

bit 4 **$\overline{RI}$:** RESET Instruction Flag bit
For details on bit operation, see Register 5-1.

bit 3 **$\overline{TO}$:** Watchdog Timer Time-out Flag bit
For details on bit operation, see Register 5-1.

bit 2 **$\overline{PD}$:** Power-Down Detection Flag bit
For details on bit operation, see Register 5-1.

bit 1 **$\overline{POR}$:** Power-on Reset Status bit
For details on bit operation, see Register 5-1.

bit 0 **$\overline{BOR}$:** Brown-out Reset Status bit
For details on bit operation, see Register 5-1.

NOTES:

17.1.2 RTCVALH AND RTCVALL REGISTER MAPPINGS

REGISTER 17-6: RESERVED REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **Unimplemented:** Read as '0'

REGISTER 17-7: YEAR: YEAR VALUE REGISTER(1)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
YRTEN3	YRTEN2	YRTEN1	YRTEN0	YRONE3	YRONE2	YRONE1	YRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-4 **YRTEN<3:0>:** Binary Coded Decimal Value of Year's Tens Digit bits
Contains a value from 0 to 9.

bit 3-0 **YRONE<3:0>:** Binary Coded Decimal Value of Year's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to the YEAR register is only allowed when RTCWREN = 1.

REGISTER 17-8: MONTH: MONTH VALUE REGISTER(1)

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **MTHTEN0:** Binary Coded Decimal Value of Month's Tens Digit bit
Contains a value of 0 or 1.

bit 3-0 **MTHONE<3:0>:** Binary Coded Decimal Value of Month's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

19.2.2 TIMER1/TIMER3 MODE SELECTION

The timers that are to be used with the capture feature (Timer1 and/or Timer3) must be running in Timer mode or Synchronized Counter mode. In Asynchronous Counter mode, the capture operation may not work. The timer to be used with each ECCP module is selected in the CCPTMRS0 register (Register 19-2).

19.2.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep the CCPxIE interrupt enable bit clear to avoid false interrupts. The interrupt flag bit, CCPxIF, should also be cleared following any such change in operating mode.

19.2.4 ECCP PRESCALER

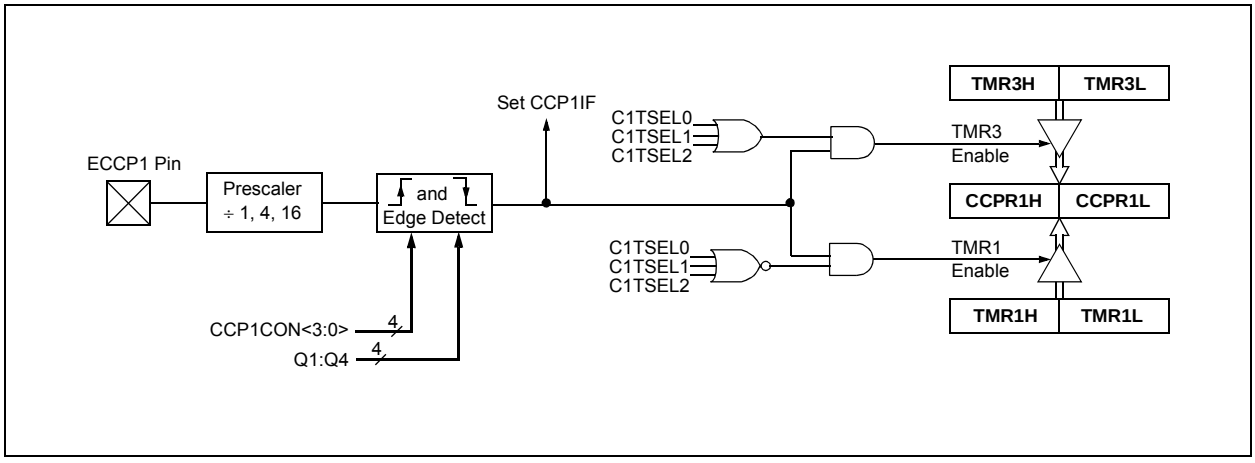
There are four prescaler settings in Capture mode; they are specified as part of the operating mode selected by the mode select bits (CCPxM<3:0>). Whenever the ECCP module is turned off, or Capture mode is disabled, the prescaler counter is cleared. This means that any Reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared; therefore, the first capture may be from a non-zero prescaler. Example 19-1 provides the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the “false” interrupt.

EXAMPLE 19-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
CLRF   ECCP1CON    ; Turn ECCP module off
MOVLW  NEW_CAPT_PS ; Load WREG with the
                   ; new prescaler mode
                   ; value and ECCP ON
MOVWF  CCP1CON     ; Load ECCP1CON with
                   ; this value
```

FIGURE 19-1: CAPTURE MODE OPERATION BLOCK DIAGRAM



REGISTER 19-6: PSTRxCON: PULSE STEERING CONTROL (1, ACCESS FBFh; 2, FB9h; 3, BANKED F1Ah)(1)

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1
CMPL1	CMPL0	—	STRSYNC	STRD	STRC	STRB	STRA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **CMPL<1:0>:** Complementary Mode Output Assignment Steering Sync bits
1 = Modulated output pin toggles between PxA and PxB for each period
0 = Complementary output assignment disabled; the STRD:STRA bits are used to determine Steering mode

bit 5 **Unimplemented:** Read as '0'

bit 4 **STRSYNC:** Steering Sync bit
1 = Output steering update occurs on next PWM period
0 = Output steering update occurs at the beginning of the instruction cycle boundary

bit 3 **STRD:** Steering Enable D bit
1 = PxD pin has the PWM waveform with polarity control from CCPxM<1:0>
0 = PxD pin is assigned to port pin

bit 2 **STRC:** Steering Enable C bit
1 = PxC pin has the PWM waveform with polarity control from CCPxM<1:0>
0 = PxC pin is assigned to port pin

bit 1 **STRB:** Steering Enable B bit
1 = PxB pin has the PWM waveform with polarity control from CCPxM<1:0>
0 = PxB pin is assigned to port pin

bit 0 **STRA:** Steering Enable A bit
1 = PxA pin has the PWM waveform with polarity control from CCPxM<1:0>
0 = PxA pin is assigned to port pin

Note 1: The PWM Steering mode is available only when the CCPxCON register bits, CCPxM<3:2> = 11 and PxM<1:0> = 00.

FIGURE 20-15: I²C SLAVE MODE TIMING WITH SEN = 1 (RECEPTION, 7-BIT ADDRESS)

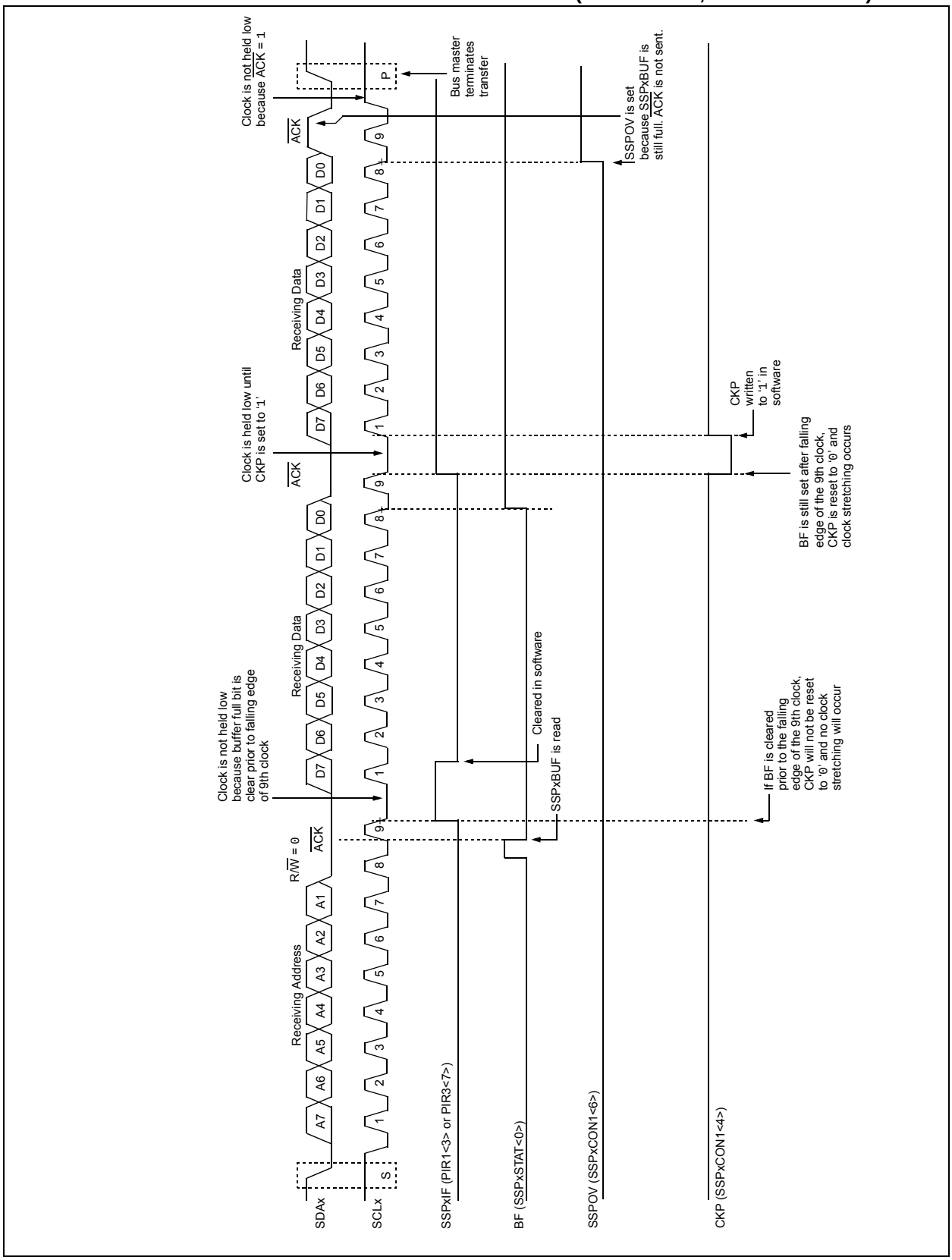
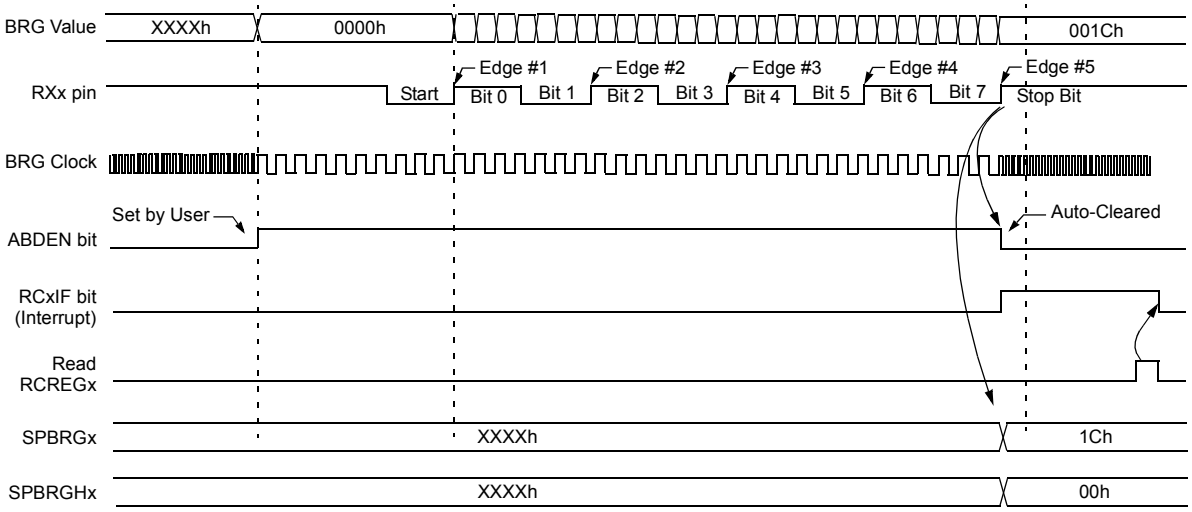
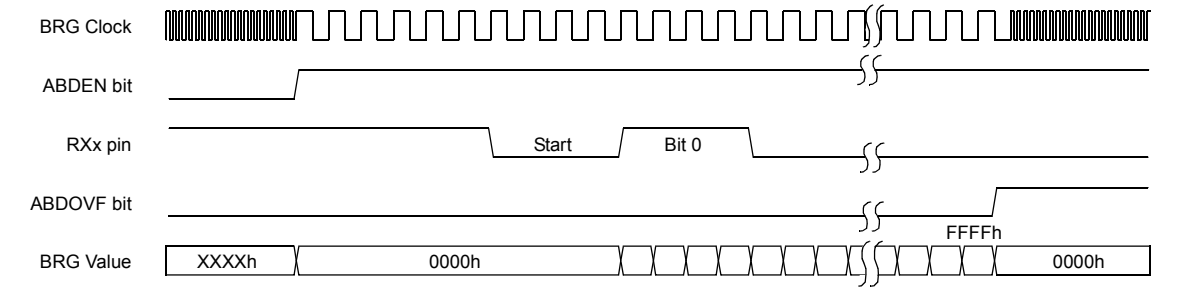


FIGURE 21-1: AUTOMATIC BAUD RATE CALCULATION



Note: The ABD sequence requires the EUSART module to be configured in Asynchronous mode and WUE = 0.

FIGURE 21-2: BRG OVERFLOW SEQUENCE



21.2.5 BREAK CHARACTER SEQUENCE

The EUSART module has the capability of sending the special Break character sequences that are required by the LIN/J2602 bus standard. The Break character transmit consists of a Start bit, followed by twelve '0' bits and a Stop bit. The Frame Break character is sent whenever the SENDB and TXEN bits (TXSTAx<3> and TXSTAx<5>) are set while the Transmit Shift Register is loaded with data.

Note that the value of data written to TXREGx will be ignored and all '0's will be transmitted.

The SENDB bit is automatically reset by hardware after the corresponding Stop bit is sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN/J2602 specification).

Note that the data value written to the TXREGx for the Break character is ignored. The write simply serves the purpose of initiating the proper sequence.

The TRMT bit indicates when the transmit operation is active or Idle, just as it does during normal transmission. See Figure 21-10 for the timing of the Break character sequence.

21.2.5.1 Break and Sync Transmit Sequence

The following sequence will send a message frame header made up of a Break, followed by an Auto-Baud Sync byte. This sequence is typical of a LIN/J2602 bus master.

1. Configure the EUSART for the desired mode.
2. Set the TXEN and SENDB bits to set up the Break character.
3. Load the TXREGx with a dummy character to initiate transmission (the value is ignored).
4. Write '55h' to TXREGx to load the Sync character into the transmit FIFO buffer.
5. After the Break has been sent, the SENDB bit is reset by hardware. The Sync character now transmits in the preconfigured mode.

When the TXREGx becomes empty, as indicated by the TXxIF, the next data byte can be written to TXREGx.

21.2.6 RECEIVING A BREAK CHARACTER

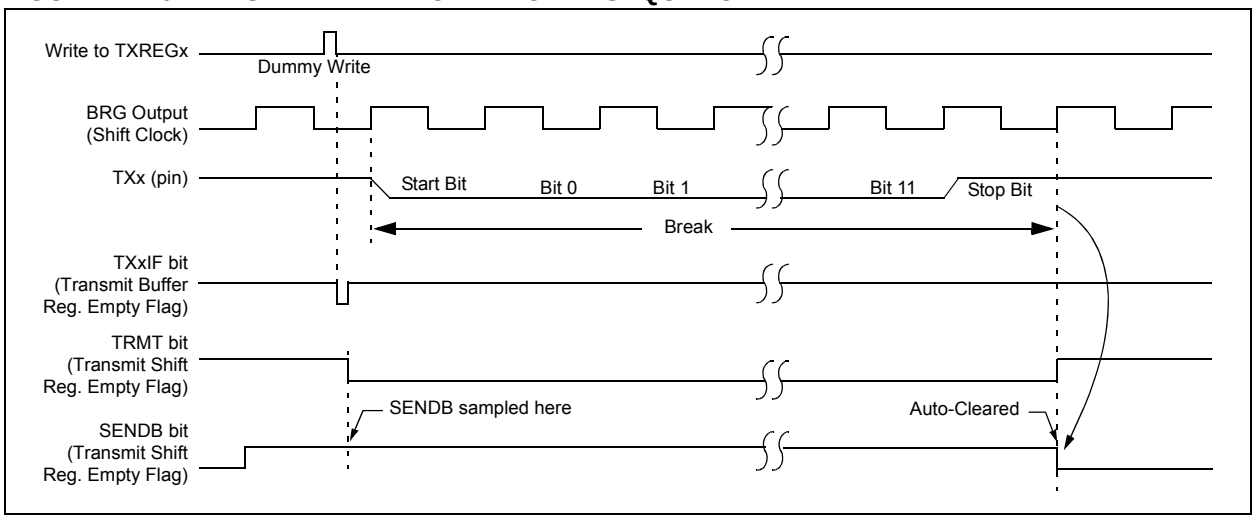
The Enhanced USART module can receive a Break character in two ways.

The first method forces configuration of the baud rate at a frequency of 9/13 of the typical speed. This allows for the Stop bit transition to be at the correct sampling location (13 bits for Break versus Start bit and 8 data bits for typical data).

The second method uses the auto-wake-up feature described in **Section 21.2.4 "Auto-Wake-up on Sync Break Character"**. By enabling this feature, the EUSART will sample the next two transitions on RXx/DTx, cause an RCxIF interrupt and receive the next data byte followed by another interrupt.

Note that following a Break character, the user will typically want to enable the Auto-Baud Rate Detect feature. For both methods, the user can set the ABDEN bit once the TXxIF interrupt is observed.

FIGURE 21-10: SEND BREAK CHARACTER SEQUENCE



22.1 A/D Acquisition Requirements

For the A/D Converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is illustrated in Figure 22-2. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor, CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ for 10-bit conversions and 1 kΩ for 12-bit conversions**. After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 22-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the 10-bit A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Equation 22-3 provides the calculation of the minimum required acquisition time, TACQ. This calculation is based on the following application system assumptions:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
VDD	=	3V → Rss = 2 kΩ
Temperature	=	85°C (system max.)

EQUATION 22-1: ACQUISITION TIME

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$

EQUATION 22-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/2048)) \bullet (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$
or
$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S)\ln(1/2048)$$

EQUATION 22-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$$
$$T_{AMP} = 0.2\ \mu s$$
$$T_{COFF} = (\text{Temp} - 25°C)(0.02\ \mu s/°C)$$
$$(85°C - 25°C)(0.02\ \mu s/°C)$$
$$1.2\ \mu s$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, $T_{COFF} = 0\ \mu s$.

$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S)\ln(1/2048)\ \mu s$$
$$-(25\ pF)(1\ k\Omega + 2\ k\Omega + 2.5\ k\Omega)\ln(0.0004883)\ \mu s$$
$$1.05\ \mu s$$
$$T_{ACQ} = 0.2\ \mu s + 1.05\ \mu s + 1.2\ \mu s$$
$$2.45\ \mu s$$

The PPBRST bit (UCON<6>) controls the Reset status when Double-Buffering mode (ping-pong buffering) is used. When the PPBRST bit is set, all Ping-Pong Buffer Pointers are set to the Even buffers. PPBRST has to be cleared by firmware. This bit is ignored in buffering modes not using ping-pong buffering.

The PKTDIS bit (UCON<4>) is a flag indicating that the SIE has disabled packet transmission and reception. This bit is set by the SIE when a SETUP token is received to allow setup processing. This bit cannot be set by the microcontroller, only cleared; clearing it allows the SIE to continue transmission and/or reception. Any pending events within the Buffer Descriptor Table (BDT) will still be available, indicated within the USTAT register's FIFO buffer.

The RESUME bit (UCON<2>) allows the peripheral to perform a remote wake-up by executing resume signaling. To generate a valid remote wake-up, firmware must set RESUME for 10 ms and then clear the bit. For more information on resume signaling, see Sections 7.1.7.5, 11.4.4 and 11.9 in the USB 2.0 Specification.

The SUSPND bit (UCON<1>) places the module and supporting circuitry in a low-power mode. The input clock to the SIE is also disabled. This bit should be set by the software in response to an IDLEIF interrupt. It should be reset by the microcontroller firmware after an ACTVIF interrupt is observed. When this bit is active, the device remains attached to the bus but the transceiver outputs remain Idle. The voltage on the V_{USB} pin may vary depending on the value of this bit. Setting this bit before a IDLEIF request will result in unpredictable bus behavior.

Note:	While in Suspend mode, a typical bus-powered USB device is limited to 2.5 mA of current. This is the complete current which may be drawn by the PIC device and its supporting circuitry. Care should be taken to assure minimum current draw when the device enters Suspend mode.

23.2.2 USB CONFIGURATION REGISTER (UCFG)

Prior to communicating over USB, the module's associated internal and/or external hardware must be configured. Most of the configuration is performed with the UCFG register (Register 23-2).The UFCG register contains most of the bits that control the system level behavior of the USB module. These include:

- Bus Speed (full speed versus low speed)
- On-Chip Pull-up Resistor Enable
- On-Chip Transceiver Enable
- Ping-Pong Buffer Usage

The UCFG register also contains two bits, which aid in module testing, debugging and USB certifications. These bits control output enable state monitoring and eye pattern generation.

Note:	The USB speed, transceiver and pull-up should only be configured during the module setup phase. It is not recommended to switch these settings while the module is enabled.

23.2.2.1 Internal Transceiver

The USB peripheral has a built-in, USB 2.0, full-speed and low-speed capable transceiver, internally connected to the SIE. This feature is useful for low-cost, single chip applications. The UTRDIS bit (UCFG<3>) controls the transceiver; it is enabled by default (UTRDIS = 0). The FSEN bit (UCFG<2>) controls the transceiver speed; setting the bit enables full-speed operation.

The on-chip USB pull-up resistors are controlled by the UPUEN bit (UCFG<4>). They can only be selected when the on-chip transceiver is enabled.

The internal USB transceiver obtains power from the V_{USB} pin. In order to meet USB signalling level specifications, V_{USB} must be supplied with a voltage source between 3.0V and 3.6V. The best electrical signal quality is obtained when a 3.3V supply is used and locally bypassed with a high quality ceramic capacitor (ex: 0.1 μF). The capacitor should be placed as close as possible to the V_{USB} and V_{SS} pins.

V_{USB} should always be maintained $\geq V_{DD}$. If the USB module is not used, but RC4 or RC5 are used as general purpose inputs, V_{USB} should still be connected to a power source (such as V_{DD}). The input thresholds for the RC4 and RC5 pins are dependent upon the V_{USB} supply level.

The D+ and D- signal lines can be routed directly to their respective pins on the USB connector or cable (for hard-wired applications). No additional resistors, capacitors or magnetic components are required as the D+ and D- drivers have controlled slew rate and output impedance intended to match with the characteristic impedance of the USB cable.

In order to achieve optimum USB signal quality, the D+ and D- traces between the microcontroller and USB connector (or cable) should be less than 19 cm long. Both traces should be equal in length and they should be routed parallel to each other. Ideally, these traces should be designed to have a characteristic impedance matching that of the USB cable.

23.9 Overview of USB

This section presents some of the basic USB concepts and useful information necessary to design a USB device. Although much information is provided in this section, there is a plethora of information provided within the USB specifications and class specifications. Thus, the reader is encouraged to refer to the USB specifications for more information (www.usb.org). If you are very familiar with the details of USB, then this section serves as a basic, high-level refresher of USB.

23.9.1 LAYERED FRAMEWORK

USB device functionality is structured into a layered framework, graphically illustrated in Figure 23-12. Each level is associated with a functional level within the device. The highest layer, other than the device, is the configuration. A device may have multiple configurations. For example, a particular device may have multiple power requirements based on Self-Power Only or Bus Power Only modes.

For each configuration, there may be multiple interfaces. Each interface could support a particular mode of that configuration.

Below the interface is the endpoint(s). Data is directly moved at this level. There can be as many as 16 bidirectional endpoints. Endpoint 0 is always a control endpoint, and by default, when the device is on the bus, Endpoint 0 must be available to configure the device.

23.9.2 FRAMES

Information communicated on the bus is grouped into 1 ms time slots, referred to as frames. Each frame can contain many transactions to various devices and endpoints. See Figure 23-8 for an example of a transaction within a frame.

23.9.3 TRANSFERS

There are four transfer types defined in the USB specification.

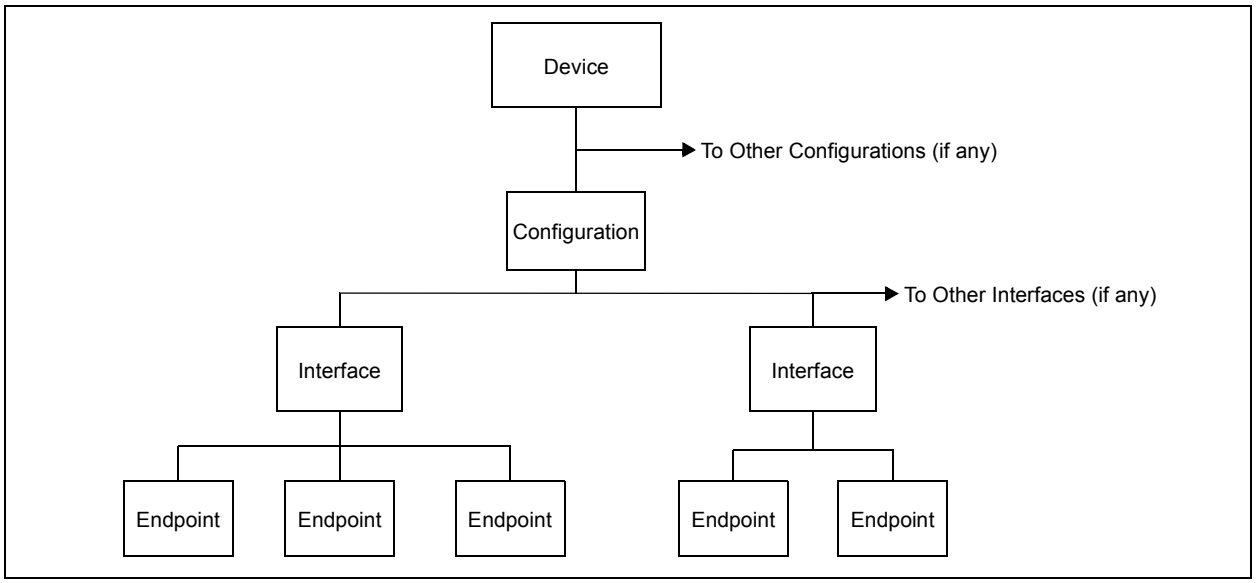
- **Isochronous:** This type provides a transfer method for large amounts of data (up to 1023 bytes) with timely delivery ensured; however, the data integrity is not ensured. This is good for streaming applications where small data loss is not critical, such as audio.
- **Bulk:** This type of transfer method allows for large amounts of data to be transferred with ensured data integrity; however, the delivery timeliness is not ensured.
- **Interrupt:** This type of transfer provides for ensured timely delivery for small blocks of data, plus data integrity is ensured.
- **Control:** This type provides for device setup control.

While full-speed devices support all transfer types, low-speed devices are limited to interrupt and control transfers only.

23.9.4 POWER

Power is available from the USB. The USB specification defines the bus power requirements. Devices may either be self-powered or bus-powered. Self-powered devices draw power from an external source, while bus-powered devices use power supplied from the bus.

FIGURE 23-12: USB LAYERS



25.1 Configuring the Comparator Voltage Reference

The comparator voltage reference module is controlled through the CVRCON register (Register 25-1). The comparator voltage reference provides two ranges of output voltage, each with 16 distinct levels. The range to be used is selected by the CVRR bit (CVRCON<5>). The primary difference between the ranges is the size of the steps selected by the CVREF Selection bits (CVR<3:0>), with one range offering finer resolution. The equations used to calculate the output of the comparator voltage reference are as follows:

EQUATION 25-1: CALCULATING OUTPUT OF THE COMPARATOR VOLTAGE REFERENCE

When CVRR = 1 and CVRSS = 0:
$CV_{REF} = ((CVR<3:0>)/24) \times (CV_{RSRC})$
When CVRR = 0 and CVRSS = 0:
$CV_{REF} = (CV_{RSRC}/4) + ((CVR<3:0>)/32) \times (CV_{RSRC})$
When CVRR = 1 and CVRSS = 1:
$CV_{REF} = ((CVR<3:0>)/24) \times (CV_{RSRC}) + V_{REF}-$
When CVRR = 0 and CVRSS = 1:
$CV_{REF} = (CV_{RSRC}/4) + ((CVR<3:0>)/32) \times (CV_{RSRC}) + V_{REF}-)$

The comparator reference supply voltage can come from either VDD and VSS, or the external VREF+ and VREF- that are multiplexed with RA2 and RA3. The voltage source is selected by the CVRSS bit (CVRCON<4>).

The settling time of the comparator voltage reference must be considered when changing the CVREF output (see Table 31-2 in **Section 31.0 "Electrical Characteristics"**).

REGISTER 25-1: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER (F53h)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CVREN	CVROE(1)	CVRR	CVRSS	CVR3	CVR2	CVR1	CVR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **CVREN:** Comparator Voltage Reference Enable bit
1 = CVREF circuit is powered on
0 = CVREF circuit is powered down

bit 6 **CVROE:** Comparator VREF Output Enable bit(1)
1 = CVREF voltage level is also output on the RA2/AN2//C2INB/C1IND/C3INB/VREF-/CVREF pin
0 = CVREF voltage is disconnected from the RA2/AN2//C2INB/C1IND/C3INB/VREF-/CVREF pin

bit 5 **CVRR:** Comparator VREF Range Selection bit
1 = 0 to 0.667 CVRSRC with CVRSRC/24 step size (low range)
0 = 0.25 CVRSRC to 0.75 CVRSRC with CVRSRC/32 step size (high range)

bit 4 **CVRSS:** Comparator VREF Source Selection bit
1 = Comparator reference source, CVRSRC = (VREF+) – (VREF-)
0 = Comparator reference source, CVRSRC = AVDD – AVSS

bit 3-0 **CVR<3:0>:** Comparator VREF Value Selection bits ($0 \le (CVR<3:0>) \le 15$)
When CVRR = 1:
$CV_{REF} = ((CVR<3:0>)/24) \bullet (CV_{RSRC})$
When CVRR = 0:
$CV_{REF} = (CV_{RSRC}/4) + ((CVR<3:0>)/32) \bullet (CV_{RSRC})$

Note 1: CVROE overrides the TRIS bit setting.

EXAMPLE 27-4: ROUTINE FOR CAPACITIVE TOUCH SWITCH

```
#include "p18cxxx.h"

#define COUNT 500                       //@ 8MHz = 125uS.
#define DELAY for(i=0;i<COUNT;i++)
#define OPENSW 1000                     //Un-pressed switch value
#define TRIP 300                        //Difference between pressed
                                        //and un-pressed switch
#define HYST 65                         //amount to change
                                        //from pressed to un-pressed
#define PRESSED 1
#define UNPRESSED 0

int main(void)
{
    unsigned int Vread;                 //storage for reading
    unsigned int switchState;
    int i;

    //assume CTMU and A/D have been setup correctly
    //see Example 25-1 for CTMU & A/D setup
    setup();

    CTMUCONHbits.CTMUEN = 1;            // Enable the CTMU
    CTMUCONLbits.EDG1STAT = 0;          // Set Edge status bits to zero
    CTMUCONLbits.EDG2STAT = 0;

    CTMUCONHbits.IDISSEN = 1;           //drain charge on the circuit
    DELAY;                              //wait 125us
    CTMUCONHbits.IDISSEN = 0;           //end drain of circuit

    CTMUCONLbits.EDG1STAT = 1;          //Begin charging the circuit
                                        //using CTMU current source
    DELAY;                              //wait for 125us
    CTMUCONLbits.EDG1STAT = 0;          //Stop charging circuit

    PIR1bits.ADIF = 0;                  //make sure A/D Int not set
    ADCON0bits.GO=1;                    //and begin A/D conv.
    while(!PIR1bits.ADIF);              //Wait for A/D convert complete

    Vread = ADRES;                      //Get the value from the A/D

    if(Vread < OPENSW - TRIP)
    {
        switchState = PRESSED;
    }
    else if(Vread > OPENSW - TRIP + HYST)
    {
        switchState = UNPRESSED;
    }
}
```

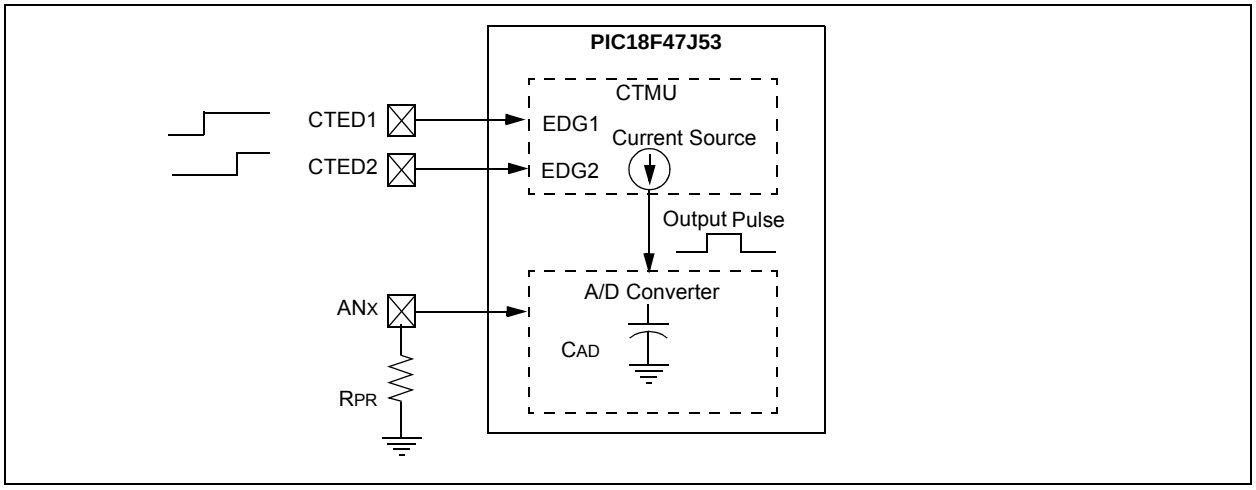
27.5 Measuring Time with the CTMU Module

Time can be precisely measured after the ratio (C/I) is measured from the current and capacitance calibration step by following these steps:

1. Initialize the A/D Converter and the CTMU.
2. Set EDG1STAT.
3. Set EDG2STAT.
4. Perform an A/D conversion.
5. Calculate the time between edges as $T = (C/I) * V$, where I is calculated in the current calibration step (**Section 27.3.1 "Current Source Calibration"**), C is calculated in the capacitance calibration step (**Section 27.3.2 "Capacitance Calibration"**) and V is measured by performing the A/D conversion.

It is assumed that the time measured is small enough that the capacitance, C_{OFFSET}, provides a valid voltage to the A/D Converter. For the smallest time measurement, always set the A/D Channel Select register (AD1CHS) to an unused A/D channel; the corresponding pin for which is not connected to any circuit board trace. This minimizes added stray capacitance, keeping the total circuit capacitance close to that of the A/D Converter itself (4-5 pF). To measure longer time intervals, an external capacitor may be connected to an A/D channel and this channel selected when making a time measurement.

FIGURE 27-3: TYPICAL CONNECTIONS AND INTERNAL CONFIGURATION FOR TIME MEASUREMENT



29.0 INSTRUCTION SET SUMMARY

The PIC18F47J53 family of devices incorporate the standard set of 75 PIC18 core instructions, as well as an extended set of 8 new instructions for the optimization of code that is recursive or that utilizes a software stack. The extended set is discussed later in this section.

29.1 Standard Instruction Set

The standard PIC18 MCU instruction set adds many enhancements to the previous PIC® MCU instruction sets, while maintaining an easy migration from these PIC MCU instruction sets. Most instructions are a single program memory word (16 bits), but there are four instructions that require two program memory locations.

Each single-word instruction is a 16-bit word divided into an opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into four basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal** operations
- **Control** operations

The PIC18 instruction set summary in Table 29-2 lists **byte-oriented**, **bit-oriented**, **literal** and **control** operations. Table 29-1 shows the opcode field descriptions.

Most **byte-oriented** instructions have three operands:

1. The file register (specified by ‘f’)
2. The destination of the result (specified by ‘d’)
3. The accessed memory (specified by ‘a’)

The file register designator, ‘f’, specifies which file register is to be used by the instruction. The destination designator, ‘d’, specifies where the result of the operation is to be placed. If ‘d’ is zero, the result is placed in the WREG register. If ‘d’ is one, the result is placed in the file register specified in the instruction.

All **bit-oriented** instructions have three operands:

1. The file register (specified by ‘f’)
2. The bit in the file register (specified by ‘b’)
3. The accessed memory (specified by ‘a’)

The bit field designator, ‘b’, selects the number of the bit affected by the operation, while the file register designator, ‘f’, represents the number of the file in which the bit is located.

The **literal** instructions may use some of the following operands:

- A literal value to be loaded into a file register (specified by ‘k’)
- The desired FSR register to load the literal value into (specified by ‘f’)
- No operand required (specified by ‘—’)

The **control** instructions may use some of the following operands:

- A program memory address (specified by ‘n’)
- The mode of the CALL or RETURN instructions (specified by ‘s’)
- The mode of the table read and table write instructions (specified by ‘m’)
- No operand required (specified by ‘—’)

All instructions are a single word, except for four double-word instructions. These instructions were made double-word to contain the required information in 32 bits. In the second word, the 4 MSbs are ‘1’s. If this second word is executed as an instruction (by itself), it will execute as a NOP.

All single-word instructions are executed in a single instruction cycle, unless a conditional test is true or the program counter is changed as a result of the instruction. In these cases, the execution takes two instruction cycles with the additional instruction cycle(s) executed as a NOP.

The double-word instructions execute in two instruction cycles.

One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true, or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs. Two-word branch instructions (if true) would take 3 μs.

Figure 29-1 shows the general formats that the instructions can have. All examples use the convention ‘nnh’ to represent a hexadecimal number.

The Instruction Set Summary, shown in Table 29-2, lists the standard instructions recognized by the Microchip MPASM™ Assembler.

Section 29.1.1 “Standard Instruction Set” provides a description of each instruction.

RRNCF **Rotate Right f (No Carry)**

Syntax: RRNCF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f<n>) → dest<n – 1>,
(f<0>) → dest<7>

Status Affected: N, Z

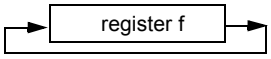
Encoding:

0100	00da	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the right. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).

If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' is '1', then the bank will be selected as per the BSR value (default).

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 29.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example 1:
```
RRNCF   REG, 1, 0
Before Instruction
    REG     =   1101 0111
After Instruction
    REG     =   1110 1011
```

Example 2:
```
RRNCF   REG, 0, 0
Before Instruction
    W       =   ?
    REG     =   1101 0111
After Instruction
    W       =   1110 1011
    REG     =   1101 0111
```

SETF **Set f**

Syntax: SETF f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: FFh → f

Status Affected: None

Encoding:

0110	100a	ffff	ffff

Description: The contents of the specified register are set to FFh.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 29.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example:
```
SETF    REG,1
Before Instruction
    REG     =   5Ah
After Instruction
    REG     =   FFh
```

31.1 DC Characteristics: Supply Voltage PIC18F47J53 Family (Industrial)

PIC18F47J53 Family			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
D001	VDD	Supply Voltage	2.15	—	3.6	V	PIC18F4XJ53, PIC18F2XJ53
D001A	VDD	Supply Voltage	2.0	—	3.6	V	PIC18LF4XJ53, PIC18LF2XJ53
D001B	VDDCORE	External Supply for Microcontroller Core	2.0	—	2.75	V	PIC18LF4XJ53, PIC18LF2XJ53
D001C	AVDD	Analog Supply Voltage	VDD – 0.3	—	VDD + 0.3	V	
D001D	AVSS	Analog Ground Potential	VSS – 0.3	—	VSS + 0.3	V	
D001E	VUSB	USB Supply Voltage	3.0	3.3	3.6	V	USB module enabled(2)
D002	VDR	RAM Data Retention Voltage(1)	1.5	—	—	V	
D003	VPOR	VDD Start Voltage to Ensure Internal Power-on Reset Signal	—	—	0.7	V	See **Section 5.3 "Power-on Reset (POR)"** for details
D004	SVDD	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	See **Section 5.3 "Power-on Reset (POR)"** for details
D005	VBOR	VDDCORE Brown-out Reset Voltage	—	2.0	—	V	PIC18F4XJ53, PIC18F2XJ53 only
D006	VDSBOR	VDD Brown-out Reset Voltage	—	1.8	—	V	DSBOREN = 1 on "LF" device or "F" device in Deep Sleep

Note 1: This is the limit to which VDDCORE can be lowered in Sleep mode, or during a device Reset, without losing RAM data.

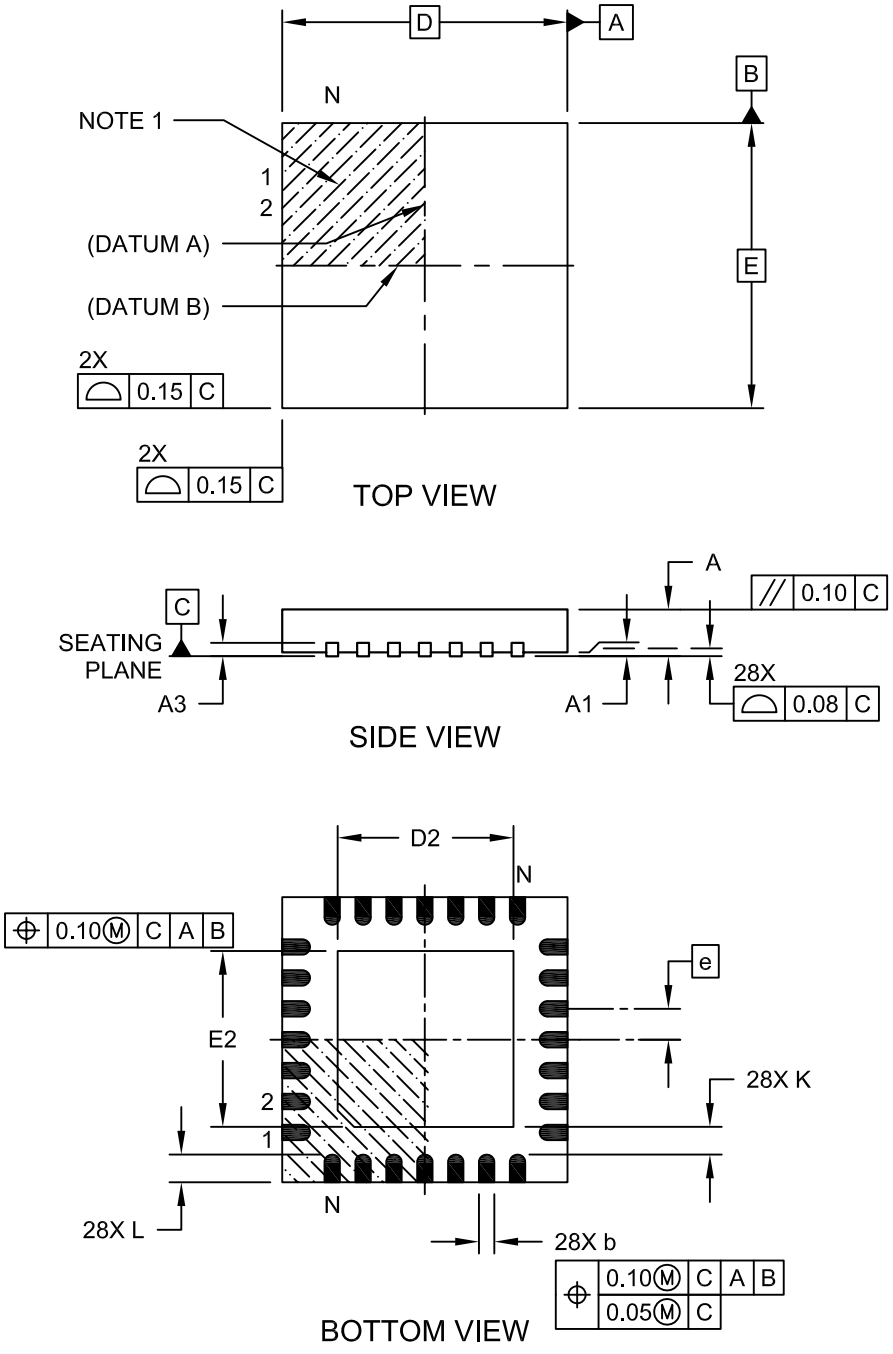
2: VUSB should always be maintained ≥ VDD, but may be left floating when the USB module is disabled and RC4/RC5 will not be used as general purpose inputs.

32.2 Package Details

The following sections give the technical details of the packages.

28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN] With 0.55 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-105C Sheet 1 of 2